

L Numb r	Hits	Search T xt	DB	Time stamp
500	5115	(sta k or stacking or stacked) and ((sub trat r int rp ser r tap) n ar5 (thr oughh le or through-h l r h l or via or opening)) and le tr d and (wire or wiring)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:53
501	1164	(stack or stacking or stacked) and ((substrate or interposer or tape) near5 (throughhole or through-hole or hole or via or opening)) and electrode and (wire or wiring) and ((first or upper or top or bottom or lower or second) near5 (chip or ic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:53
502	990	(stack or stacking or stacked) and ((substrate or interposer or tape) near5 (throughhole or through-hole or hole or via or opening)) and electrode and (wire or wiring) and ((first or upper or top or bottom or lower or second) near5 (chip or ic)) and (mount or mounted or mounting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:54
503	657	(stack or stacking or stacked) and ((substrate or interposer or tape) near5 (throughhole or through-hole or hole or via or opening)) and electrode and (wire or wiring) and ((first or upper or top or bottom or lower or second) near5 (chip or ic)) and (mount or mounted or mounting) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:54
504	395	(stack or stacking or stacked) and ((substrate or interposer or tape) near5 (throughhole or through-hole or hole or via or opening)) and electrode and (wire or wiring) and ((first or upper or top or bottom or lower or second) near5 (chip or ic)) and (mount or mounted or mounting) and adhesive and ((insulating or dielectric or nonconductive or non-conductive or nonconducting or non-conducting) near5 (substrate or interposer or tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:55
505	84	(stack or stacking or stacked).ti,ab,clm. and ((substrate or interposer or tape) near5 (throughhole or through-hole or hole or via or opening)).ti,ab,clm. and electrode and (wire or wiring) and ((first or upper or top or bottom or lower or second) near5 (chip or ic)) and (mount or mounted or mounting) and adhesive and ((insulating or dielectric or n n nductiv r non-conductive r non onducting or non-conducting) near5 (ubstrate r interp ser r tape))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:56

506	41	(stack or stacking or stacked).ti,ab,clm. and ((substrate or interposer or tape) near5 (through-hole or through-hole or via or opening)).ti,ab,clm. and electrode and (wire or wiring) and ((first or upper or top or bottom or lower or second) near5 (chip or ic)) and (mount or mounted or mounting) and adhesive and ((insulating or dielectric or nonconductive or non-conductive or nonconducting or non-conducting) near5 (substrate or interposer or tape)).ti,ab,clm.	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:56
507	19	(stack or stacking or stacked).ti,ab,clm. and ((substrate or interposer or tape) near5 (through-hole or through-hole or hole or via or opening)).ti,ab,clm. and electrode.ti,ab,clm. and (wire or wiring) and ((first or upper or top or bottom or lower or second) near5 (chip or ic)) and (mount or mounted or mounting) and adhesive and ((insulating or dielectric or nonconductive or non-conductive or nonconducting or non-conducting) near5 (substrate or interposer or tape)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:56
508	18	(stack or stacking or stacked).ti,ab,clm. and ((substrate or interposer or tape) near5 (through-hole or through-hole or hole or via or opening)).ti,ab,clm. and electrode.ti,ab,clm. and (wire or wiring).ti,ab,clm. and ((first or upper or top or bottom or lower or second) near5 (chip or ic)) and (mount or mounted or mounting) and adhesive and ((insulating or dielectric or nonconductive or non-conductive or nonconducting or non-conducting) near5 (substrate or interposer or tape)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:56
509	9	(stack or stacking or stacked).ti,ab,clm. and ((substrate or interposer or tape) near5 (through-hole or through-hole or hole or via or opening)).ti,ab,clm. and electrode.ti,ab,clm. and (wire or wiring).ti,ab,clm. and ((first or upper or top or bottom or lower or second) near5 (chip or ic)).ti,ab,clm. and (mount or mounted or mounting) and adhesive and ((insulating or dielectric or nonconductive or non-conductive or nonconducting or non-conducting) near5 (substrate or interposer or tape)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:56